2. IPI-VVD Symposium
Simulation in Packaging Development
June 11th and 12th 2014
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Simulation in Packaging Development

June 11th  Simulation for Packaging Processes

09:30  Registration

**Session 1 – Simulation of Packaging Processes and Packaging Material Production Processes**

09:45  Welcome and overview on tools and approaches for packaging related simulations
       *Sascha Bach, Technische Universität Dresden / IPI*

       Added value of numerical simulation to the packaging industry  *Dr. Serge Batkam, Pack 3.0*

       Simulation programs for production of films and packages
       *Prof. Chistyakova, St. Petersburg State Institute of Technology*

       Appropriate material testing & analysis is the key to successful simulation in packaging
       *Dr. Christian Leppin, Suisse Technology Partners*

12:20  Lunch

13:30  Computer simulation of thermoforming and blow molding and its practical achievements in
       optimization praxis  *Dr. Karel Kouba, Accuform*

       Modeling of the seal integrity  *Dr. Jef van Dun, DOW Europe GmbH*

       Finite-element simulations for investigations of the effects of parameters and tool geometry in
       heat sealing processes  *Sascha Bach, Technische Universität Dresden / IPI*

15:10  Coffee Break

**Session 2 – Processes and Sequences in Packaging Machines and Plants**

15:40  Shorter time to market with simulation support in packaging machine development
       *Anton Fritsch, ITQ*

       Improvement of effectiveness of a packaging line using statistical simulations
       *Prof. Matthias Weiß, University of Applied Science Hannover, IKA Dresden*

       Discrete event simulation handling processes in packaging plants
       *Dr. Holger Pitsch, Incontrol Simulation Solutions*

       Conclusions and Discussions on Day 1
       *Sascha Bach, Technische Universität Dresden / IPI*

17:45  End

**Evening Event**

19:00  Social Dinner at Chlosterhof Stein am Rhein
       [www.chlosterhof.ch](http://www.chlosterhof.ch)

[www.ipi.eu](http://www.ipi.eu)
About the Symposium

Simulation is being used increasingly in process design and optimization. Packaging technology often presents a complicated, interdisciplinary set of challenges including the interaction of packaging and fillgoods, dynamic processes as well as the mechanical components of packaging and packing equipment. The complex interplay of these factors often cannot be tested efficiently by Trial and Error. However, modern simulation technology can address this.

The IPI-VVD Symposium will explore the wide range of applications which simulation can help with – from the production of packaging materials to different steps in the packaging process, quality assurance and packing lines – and will be presented by highly experienced experts in the use of simulation techniques. The Symposium is aimed at R&D specialists working in the packaging sector, packing companies, packaging and packing equipment designers and packaging manufacturers who need to understand the options available to use simulation in the design and improvement of packaging processes and are interested in developing their network of contacts in this field.

June 12th  Simulation for Packaging Design and Optimization

09:15  Welcome

Session 3 – Packaging Design and Virtual Packaging Testing with Simulation
09:20  Simulation of packaging design and its effect in the shelf environment  *Esko Artworks*
Modeling of packaging film design in order to predict cost and reduce development cycle time  
*Dr. Karlheinz Hausmann, DuPont*
Designing packages: A virtual engineering perspective  *Alberto Mameli, Tetra Pack*

Session 4 - Simulation for Product Safety and Improved Packaging Quality
11:10  Modeling of bag handle failure  *Colmar Wocke, DOW Europe GmbH*
Shelf-life prediction in pharmaceutical packaging: diffusion in thermo- and cold formed blisters  
*Mathias Schellenberg, Suisse Technology Partners*
12:30  Lunch

13:30  Software for simulations in packaging development  *Dr. Tarik El-Dsoki, MSC. Software GmbH*
Anticounterfeit for polymer films for packaging  
*Prof. Christian Kohlert, Klöckner Pentaplast GmbH & Co. KG*
Apps and simulation tools to set up sealing and converting processes easily  
*Prof. Steven Abbott, Abbott TCNF Ltd*
16:00  Closing discussion and end of the symposium
You are invited to stay after the end of the conference in the conference hotel to continue discussions with speakers and participants

www.ipi.eu
Details

Date       June 11th / 12th 2014
Language   English
Fee        CHF 1’250.-* (both days)
           CHF 750.-* (one day)
           incl. VAT, lunch, dinner and documentation
           *or Euro equivalent at actual exchange rate
Location  Hotel Chlosterhof
           Oehningerstrasse 2
           8260 Stein am Rhein
           Switzerland
           www.chlosterhof.ch
Registration www.ipi.eu/ipi-events/registration
Deadline   June 6th 2014

Hotel Recommendation
Until May 28th a contingent of rooms is reserved for the IPI – VVD Symposium in the
Hotel Chlosterhof for CHF 170.- per night.
Please mention the IPI – VVD Symposium to profit from the special rate.

Venue
Stein am Rhein – a charming little town well known for its beautiful historic city-centre. With its thousand-year-old history, wonderful half-timbered houses, the magnificent frescoes and the unique landscape along the shores of the Rhine river and ideal place to meet, network and exchange and create new ideas for your business.